

# Complementary MOSFET

## ELM16604EA-S

### ■General Description

ELM16604EA-S uses advanced trench technology to provide excellent  $R_{ds(on)}$  and low gate charge.

### ■Features

- |  |   |
|--|---|
| N-channel                              | P-channel                               |
| $V_{ds}=20V$                           | $V_{ds}=-20V$                           |
| $I_d=3.4A(V_{gs}=4.5V)$                | $I_d=-2.5A(V_{gs}=-4.5V)$               |
| $R_{ds(on)} < 60m\Omega(V_{gs}=4.5V)$  | $R_{ds(on)} < 110m\Omega(V_{gs}=-4.5V)$ |
| $R_{ds(on)} < 75m\Omega(V_{gs}=2.5V)$  | $R_{ds(on)} < 140m\Omega(V_{gs}=-2.5V)$ |
| $R_{ds(on)} < 100m\Omega(V_{gs}=1.8V)$ | $R_{ds(on)} < 200m\Omega(V_{gs}=-1.8V)$ |

### ■Maximum Absolute Ratings

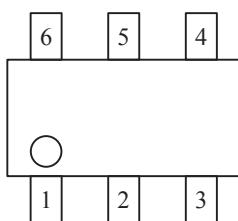
Parameter	Symbol	N-ch (Max.)	P-ch (Max.)	Unit	Note
Drain-source voltage	$V_{ds}$	20	-20	V	
Gate-source voltage	$V_{gs}$	$\pm 8$	$\pm 8$	V	
Continuous drain current	$I_d$	3.4	-2.5	A	1
		2.7	-2.0		
Pulsed drain current	$I_{dm}$	15	-15	A	2
Power dissipation	$P_d$	1.15	1.15	W	
		0.73	0.73		
Junction and storage temperature range	$T_j, T_{stg}$	-55 to 150	-55 to 150	°C	

### ■Thermal Characteristics

Parameter	Symbol	Device	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	$R_{\theta ja}$	N-ch	78	110	°C/W	1
Maximum junction-to-ambient			106	150	°C/W	
Maximum junction-to-lead			64	80	°C/W	3
Maximum junction-to-ambient	$R_{\theta ja}$	P-ch	78	110	°C/W	1
Maximum junction-to-ambient			106	150	°C/W	
Maximum junction-to-lead			64	80	°C/W	3

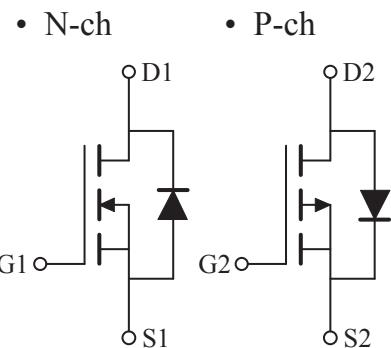
### ■Pin configuration

SOT-26(TOP VIEW)



Pin No.	Pin name
1	GATE1
2	SOURCE2
3	GATE2
4	DRAIN2
5	SOURCE1
6	DRAIN1

### ■Circuit



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### ■Electrical Characteristics (N-ch)

T<sub>a</sub>=25°C

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit	
<b>STATIC PARAMETERS</b>								
Drain-source breakdown voltage	BV <sub>dss</sub>	Id=250μA, V <sub>gs</sub> =0V		20			V	
Zero gate voltage drain current	Id <sub>ss</sub>	V <sub>ds</sub> =16V, V <sub>gs</sub> =0V	T <sub>j</sub> =55°C			1	μA	
						5		
Gate-body leakage current	I <sub>gss</sub>	V <sub>ds</sub> =0V, V <sub>gs</sub> =±8V				100	nA	
Gate threshold voltage	V <sub>gs(th)</sub>	V <sub>ds</sub> =V <sub>gs</sub> , Id=250μA		0.4	0.6	1.0	V	
On state drain current	Id(on)	V <sub>gs</sub> =4.5V, V <sub>ds</sub> =5V		15			A	
Static drain-source on-resistance	R <sub>ds(on)</sub>	V <sub>gs</sub> =4.5V, Id=3.4A			46	60	mΩ	
		T <sub>j</sub> =125°C			63	80		
		V <sub>gs</sub> =2.5V, Id=3A			57	75		
		V <sub>gs</sub> =1.8V, Id=2A			72	100		
Forward transconductance	G <sub>fs</sub>	V <sub>ds</sub> =5V, Id=3.4A			10		S	
Diode forward voltage	V <sub>sd</sub>	Is=1A, V <sub>gs</sub> =0V			0.76	1.00	V	
Max.body-diode continuous current	Is					2	A	
<b>DYNAMIC PARAMETERS</b>								
Input capacitance	C <sub>iss</sub>	V <sub>gs</sub> =0V, V <sub>ds</sub> =10V, f=1MHz			436	570	pF	
Output capacitance	C <sub>oss</sub>				66		pF	
Reverse transfer capacitance	C <sub>rss</sub>				44		pF	
Gate resistance	R <sub>g</sub>	V <sub>gs</sub> =0V, V <sub>ds</sub> =0V, f=1MHz			3	4	Ω	
<b>SWITCHING PARAMETERS</b>								
Total gate charge	Q <sub>g</sub>	V <sub>gs</sub> =4.5V, V <sub>ds</sub> =10V, Id=3.4A			6.2	8.1	nC	
Gate-source charge	Q <sub>gs</sub>				1.6		nC	
Gate-drain charge	Q <sub>gd</sub>				0.5		nC	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>gs</sub> =5V, V <sub>ds</sub> =10V R <sub>l</sub> =3Ω, R <sub>gen</sub> =3Ω			5.5		ns	
Turn-on rise time	t <sub>r</sub>				6.3		ns	
Turn-off delay time	t <sub>d(off)</sub>				40.0		ns	
Turn-off fall time	t <sub>f</sub>				12.7		ns	
Body-diode reverse recovery time	t <sub>rr</sub>	I <sub>f</sub> =3.4A, dI/dt=100A/μs			12.3	16.0	ns	
Body-diode reverse recovery charge	Q <sub>rr</sub>	I <sub>f</sub> =3.4A, dI/dt=100A/μs			3.5		nC	

#### NOTE :

1. The value of R<sub>θja</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board of 2oz. Copper, in still air environment with T<sub>a</sub>=25°C. The value in any given applications depends on the user's specific board design, The current rating is based on the t ≤ 10s thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The R<sub>θja</sub> is the sum of the thermal impedance from junction to lead R<sub>θjl</sub> and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80μs pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25°C. The SOA curve provides a single pulse rating.



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## ■ Typical Electrical and Thermal Characteristics (N-ch)

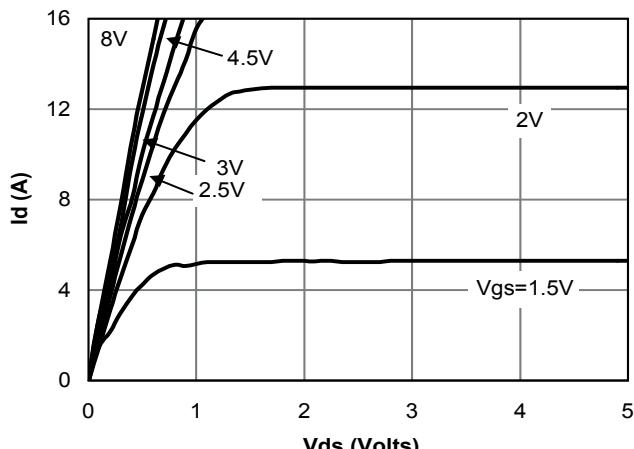


Fig 1: On-Region Characteristics

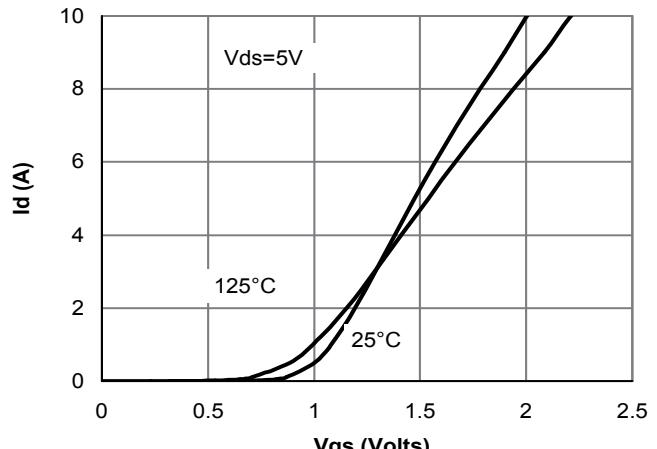


Figure 2: Transfer Characteristics

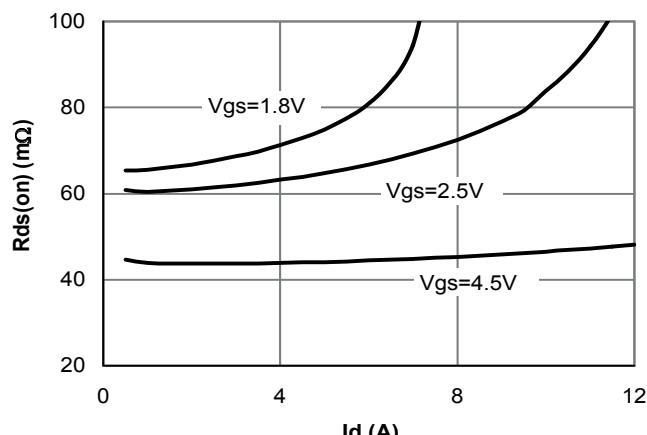


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

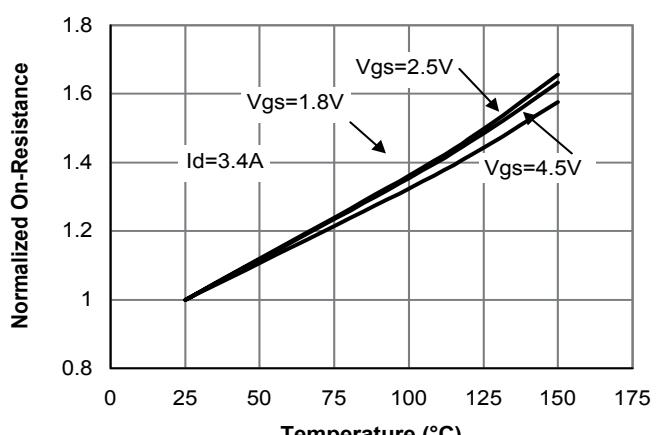


Figure 4: On-Resistance vs. Junction Temperature

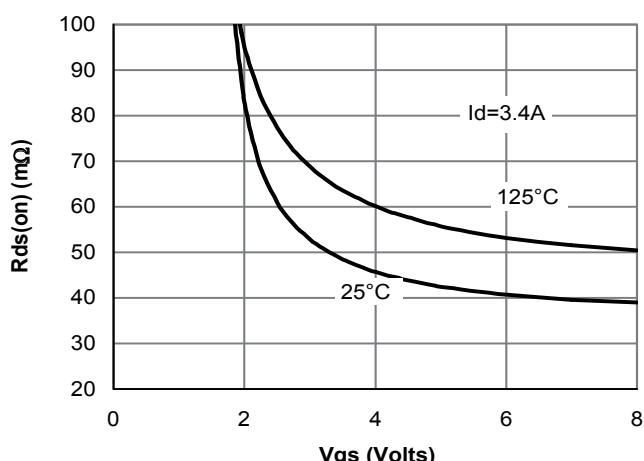


Figure 5: On-Resistance vs. Gate-Source Voltage

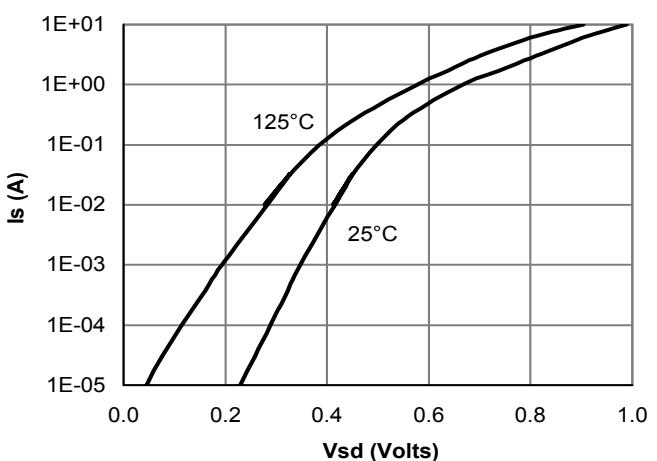


Figure 6: Body-Diode Characteristics

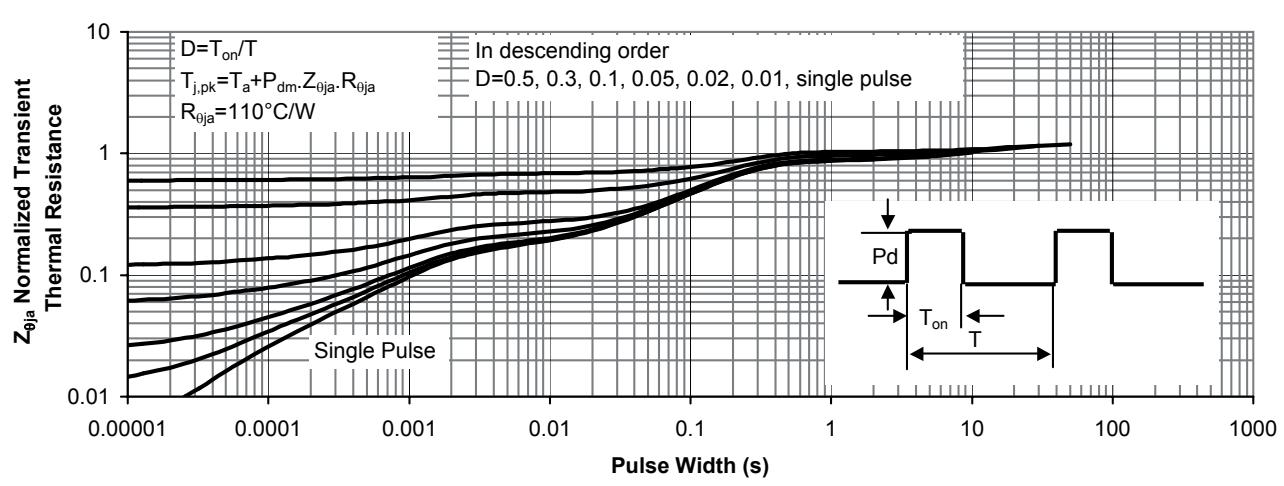
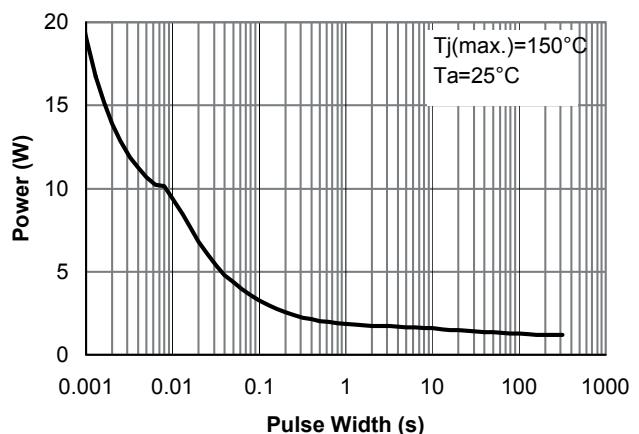
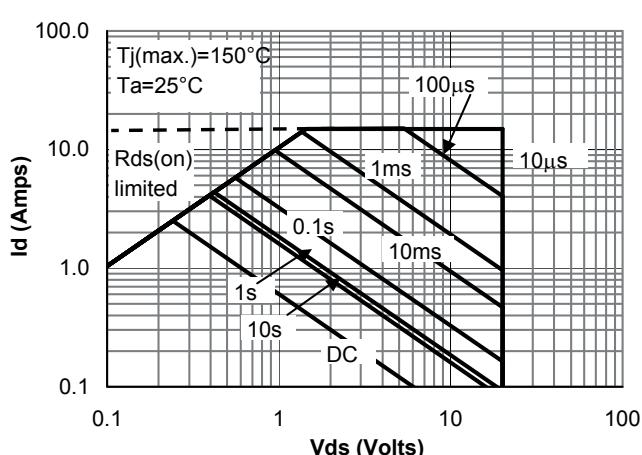
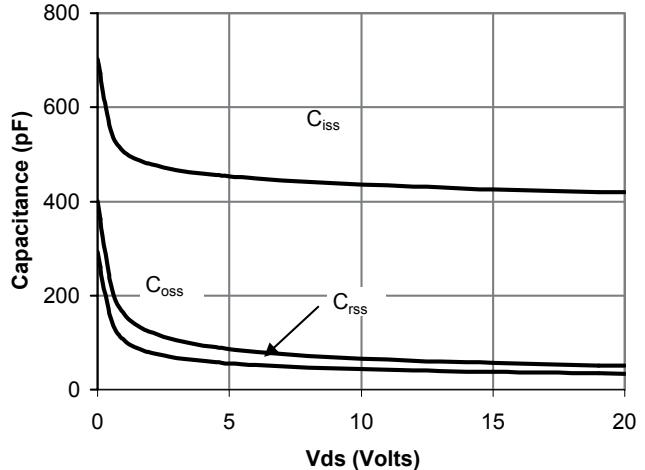
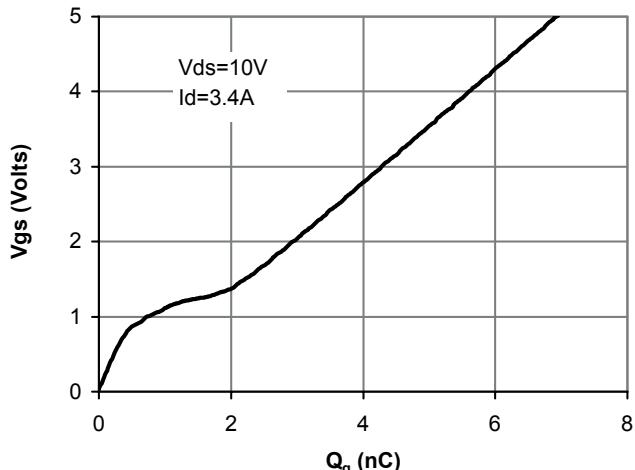
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### ■Electrical Characteristics (P-ch)

T<sub>a</sub>=25°C

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit	
<b>STATIC PARAMETERS</b>								
Drain-source breakdown voltage	BV <sub>dss</sub>	Id=-250μA, V <sub>gs</sub> =0V		-20			V	
Zero gate voltage drain current	Id <sub>ss</sub>	V <sub>ds</sub> =-16V, V <sub>gs</sub> =0V	T <sub>j</sub> =55°C			-1	μA	
						-5		
Gate-body leakage current	I <sub>gss</sub>	V <sub>ds</sub> =0V, V <sub>gs</sub> =±8V				±100	nA	
Gate threshold voltage	V <sub>gs(th)</sub>	V <sub>ds</sub> =V <sub>gs</sub> , Id=-250μA		-0.30	-0.55	-1.00	V	
On state drain current	Id(on)	V <sub>gs</sub> =-4.5V, V <sub>ds</sub> =-5V		-15			A	
Static drain-source on-resistance	R <sub>ds(on)</sub>	V <sub>gs</sub> =-4.5V Id=-2.5A	T <sub>j</sub> =125°C		86	110	mΩ	
					116	145		
		V <sub>gs</sub> =-2.5V, Id=-2A			113	140	mΩ	
		V <sub>gs</sub> =-1.8V, Id=-1A			151	200	mΩ	
Forward transconductance	G <sub>fs</sub>	V <sub>ds</sub> =-5V, Id=-3A		4	6		S	
Diode forward voltage	V <sub>sd</sub>	Is=-1A, V <sub>gs</sub> =0V			-0.78	-1.00	V	
Max. body-diode continuous current	Is					-2	A	
<b>DYNAMIC PARAMETERS</b>								
Input capacitance	C <sub>iss</sub>	V <sub>gs</sub> =0V, V <sub>ds</sub> =-10V, f=1MHz			540	700	pF	
Output capacitance	C <sub>oss</sub>				72		pF	
Reverse transfer capacitance	C <sub>rss</sub>				49		pF	
Gate resistance	R <sub>g</sub>	V <sub>gs</sub> =0V, V <sub>ds</sub> =0V, f=1MHz			12.0	15.6	Ω	
<b>SWITCHING PARAMETERS</b>								
Total gate charge	Q <sub>g</sub>	V <sub>gs</sub> =-4.5V, V <sub>ds</sub> =-10V Id=-2.5A			6.1	8.0	nC	
Gate-source charge	Q <sub>gs</sub>				0.6		nC	
Gate-drain charge	Q <sub>gd</sub>				1.6		nC	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>gs</sub> =-4.5V, V <sub>ds</sub> =-10V R <sub>l</sub> =3.9Ω, R <sub>gen</sub> =3Ω			10		ns	
Turn-on rise time	t <sub>r</sub>				12		ns	
Turn-off delay time	t <sub>d(off)</sub>				44		ns	
Turn-off fall time	t <sub>f</sub>				22		ns	
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>f</sub> =-2.5A, dI/dt=100A/μs			21.0	28.0	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>	I <sub>f</sub> =-2.5A, dI/dt=100A/μs			7.5		nC	

#### NOTE :

1. The value of R<sub>θja</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board of 2oz. Copper, in still air environment with T<sub>a</sub>=25°C. The value in any given applications depends on the user's specific board design, The current rating is based on the t ≤ 10s thermal resistance rating.
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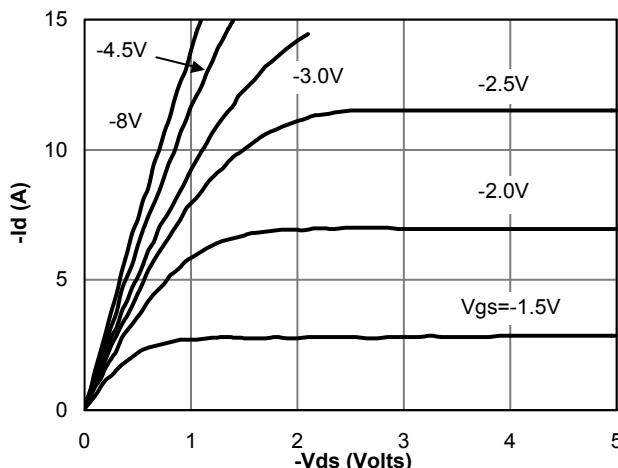


Fig 1: On-Region Characteristics

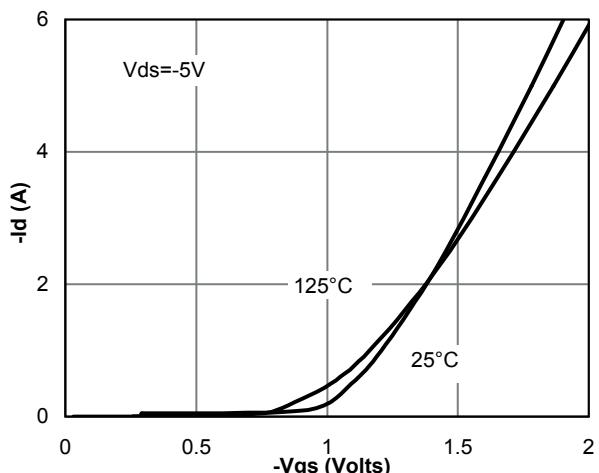


Figure 2: Transfer Characteristics

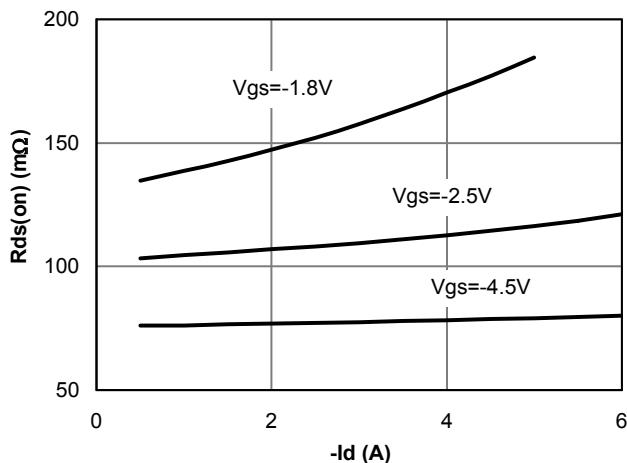


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

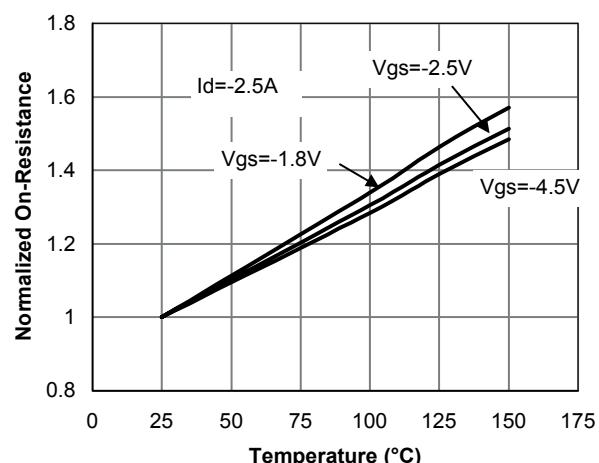


Figure 4: On-Resistance vs. Junction Temperature

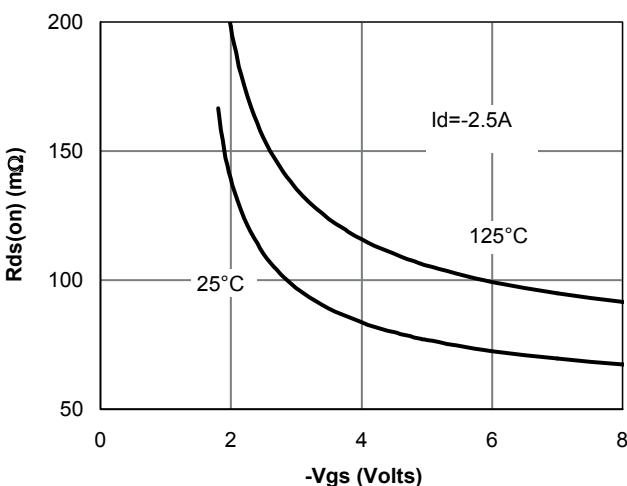


Figure 5: On-Resistance vs. Gate-Source Voltage

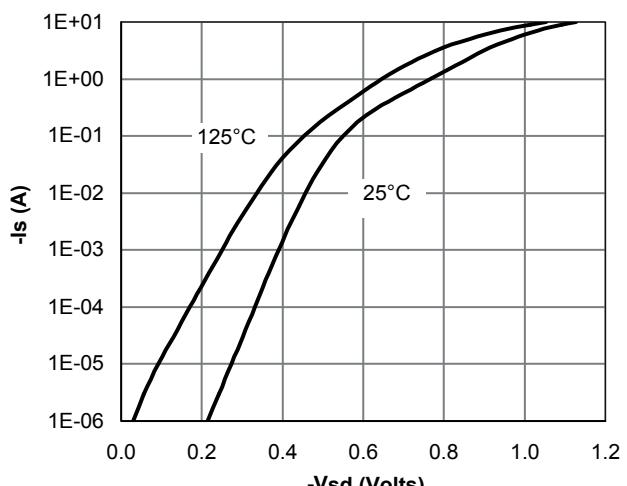


Figure 6: Body-Diode Characteristics

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